

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	38	(@ad<"20000118") and (257/782,783.ccls. or 438/118,406.ccls.) and ((partial\$3 near cur\$3) with (adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:23
L2	7	L1 and ((mask or resist) with (adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:24
L3	39	(@ad<"20000118") and (257/782,783.ccls. or 438/118,406.ccls.) and ((partial\$3 near cur\$3) with (underfill or adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:24
L4	7	L3 and ((mask or resist) with (adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:25
L5	483	(@ad<"20000118") and (chip or die) and ((partial\$3 near cur\$3) with (underfill or adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:41
L6	48	L5 and ((mask or resist) with (adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:36
L7	48	L5 and ((mask or resist) with (underfill or adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:25

## EAST Search History

L8	78	L5 and ((passivation or mask or resist) with (adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:40
L9	79	L5 and ((passivation or mask or resist) with (underfill or adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:37
L10	65	L9 and (encapsulation or encapsulant or epoxy)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:37
L11	65	L9 and (encapsulation or encapsulant or epoxy)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:37
L12	31	L9 not L7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:38
L13	2488	(solder adj (passivation or mask or resist)) with (underfill or adhesive or interface or bonding)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:41
L14	12	l13 and (@ad<"20000118") and (chip or die) and ((partial\$3 near cur\$3) with (underfill or adhesive or interface or bonding))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:42

## EAST Search History

L15	12	l13 and (@ad<"20000118") and (chip or die) and ((partial\$3 near cur\$3) with (underfill or adhesive or interface or bonding or film or layer or sheet))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 16:42
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